

PCT

WORLD INTELLECTUAL PROPERTY ORGANIZATION
International Bureau



INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification ⁷ : C08K 5/14, 5/23, C08G 63/91, C08F 283/01, 299/04, C08L 67/06, 77/12		A1	(11) International Publication Number: WO 00/55247 (43) International Publication Date: 21 September 2000 (21.09.00)
(21) International Application Number: PCT/JP00/01444 (22) International Filing Date: 10 March 2000 (10.03.00)		(81) Designated States: CN, US, European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE).	
(30) Priority Data: 11/68644 • 15 March 1999 (15.03.99) JP 11/218913 2 August 1999 (02.08.99) JP 11/259470 13 September 1999 (13.09.99) JP		Published <i>With international search report.</i>	
(71) Applicant (for all designated States except US): KAO CORPORATION [JP/JP]; 14-10, Nihonbashi Kayabacho 1-chome, Chuo-ku, Tokyo 103-8210 (JP).			
(72) Inventors; and (75) Inventors/Applicants (for US only): SAKUMA, Tadashi [JP/JP]; Kao Corporation, Research Laboratories, 1334, Minato, Wakayama-shi, Wakayama 640-8580 (JP). KAWABE, Kuniyasu [JP/JP]; Kao Corporation, Research Laboratories, 1334, Minato, Wakayama-shi, Wakayama 640-8580 (JP).			
(74) Agent: HOSODA, Yoshinori; Hosoda International Patent Office, Otemae M2 Building, 8-1, Tanimachi 2-chome, Chuo-ku, Osaka-shi, Osaka 540-0012 (JP).			
(54) Title: WATER-BASED RESIN COMPOSITION			
(57) Abstract			
<p>A thermosetting water-based resin composition comprising an oil-soluble initiator of which a temperature for one-minute half-life is from 90° to 270 °C and a polycondensation resin comprising an unsaturated dicarboxylic acid having a radical-polymerizable unsaturated bond or an acid anhydride thereof as at least one constituent monomer, wherein the polycondensation resin has an acid value of from 3 to 100 mg KOH/g, and wherein said oil-soluble initiator is present in said polycondensation resin; a process for preparing the thermosetting water-based resin composition; a molding compound composition comprising the water-based resin composition; and a molding product prepared by molding the molding compound composition.</p>			